



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

October 8, 2009

Applicants: Atsushi YABE et al  
For: ELECTROLESS COPPER PLATING SOLUTION  
Serial No.: 10/576 231 Group: 1792  
Confirmation No.: 7188  
Filed: April 14, 2006 Examiner: Bareford  
International Application No.: PCT/JP2004/011327  
International Filing Date: July 30, 2004  
Atty. Docket No.: 4700.P0327US

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

RESPONSE

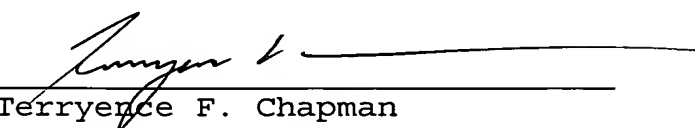
Sir:

In response to the Office Action dated July 17, 2009,  
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
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Alexandria, VA 22313-1450, on October 8, 2009.

  
Terryence F. Chapman